

WP1384AL/GD

3.4 mm Single-Level Circuit Board Indicator

DESCRIPTION

• The Green source color devices are made with Gallium Phosphide Green Light Emitting Diode

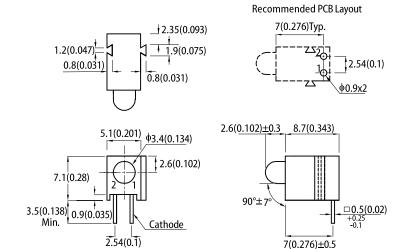
FEATURES

- · Pre-trimmed leads for pc mounting
- · Can be assembled with each other
- · Black case enhances contrast ratio
- · High reliability-life measured in years
- Housing UL rating: 94V-0
- · Housing material: Type 66 nylon
- · RoHS compliant

APPLICATIONS

- Status indicator
- Illuminator
- · Signage applications
- · Decorative and entertainment lighting
- · Commercial and residential architectural lighting

PACKAGE DIMENSIONS



- 1. All dimensions are in millimeters (inches)
- 1. Air unimissions are in minimineters (inches).
 2. Tolerance is ±0.25(0.01") unless otherwise noted.
 3. Lead spacing is measured where the leads emerge from the package.
 4. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

SELECTION GUIDE

Part Number		Long Type	Iv (mcd) @ 10mA [2]		Viewing Angle [1]
rait Number		Min.	Тур.	201/2	
WP1384AL/GD	■ Green (GaP)	Green Diffused	10	20	60°

Notes.

1. 01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

2. Luminous intensity / luminous flux: +/-15%.

3. Luminous intensity value is traceable to CIE127-2007 standards.



ELECTRICAL / OPTICAL CHARACTERISTICS at T_A=25°C

Parameter	Symbol	Emitting Color	Value		I I m i 4
Parameter			Тур.	Max.	Unit
Wavelength at Peak Emission $I_F = 10 \text{mA}$	λ_{peak}	Green	565	-	nm
Dominant Wavelength I _F = 10mA	λ _{dom} ^[1]	Green	568	-	nm
Spectral Bandwidth at 50% Φ REL MAX I _F = 10mA	Δλ	Green	30	-	nm
Capacitance	С	Green	15	-	pF
Forward Voltage I _F = 10mA	V _F ^[2]	Green	2	2.4	V
Reverse Current (V _R = 5V)	I _R	Green	-	10	μА
Temperature Coefficient of λ_{peak} I_F = 10mA, -10°C \leq T \leq 85°C	TC_{\lambdapeak}	Green	0.1	-	nm/°C
Temperature Coefficient of λ_{dom} I_F = 10mA, -10°C \leq T \leq 85°C	TC_{\lambdadom}	Green	0.06	-	nm/°C
Temperature Coefficient of V_F I_F = 10mA, -10°C \leq T \leq 85°C	TC _V	Green	-2	-	mV/°C

Notes:

2. Forward voltage: ±0.1V.
3. Wavelength value is traceable to CIE127-2007 standards.

ABSOLUTE MAXIMUM RATINGS at T_A=25°C

Parameter	Symbol	Value	Unit	
Power Dissipation	P _D	62.5	mW	
Reverse Voltage	V _R	5	V	
Junction Temperature	T _j	110	°C	
Operating Temperature	T _{op}	-40 To +85	°C	
Storage Temperature	T _{stg}	-40 To +85	°C	
DC Forward Current	I _F	25	mA	
Peak Forward Current	I _{FM} ^[1]	140	mA	
Electrostatic Discharge Threshold (HBM)	-	8000	V	
Thermal Resistance (Junction / Ambient)	R _{th JA} [2]	650	°C/W	
Thermal Resistance (Junction / Solder point)	R _{th JS} [2]	420	°C/W	
Lead Solder Temperature [3]		260°C For 3 Seconds		
Lead Solder Temperature [4]		260°C For 5 Seconds		

^{1.} The dominant wavelength (λd) above is the setup value of the sorting machine. (Tolerance λd : ± 1 nm.)

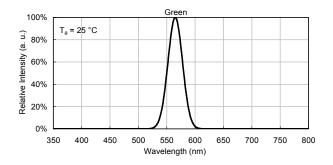
^{4.} Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

Notes:
1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. R_{in JA}, R_{in JS} Results from mounting on PC board FR4 (pad size ≥ 16 mm² per pad).
3. 2mm below package base.
4. 5mm below package base.
5. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

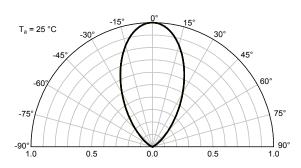


TECHNICAL DATA

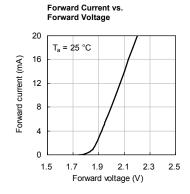
RELATIVE INTENSITY vs. WAVELENGTH

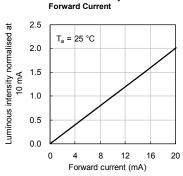


SPATIAL DISTRIBUTION

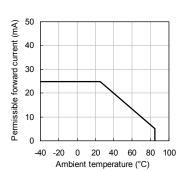




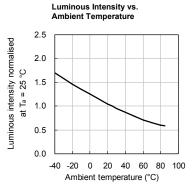




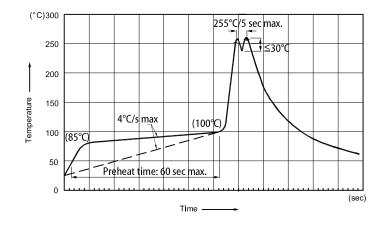
Luminous Intensity vs.



Forward Current Derating Curve



RECOMMENDED WAVE SOLDERING PROFILE

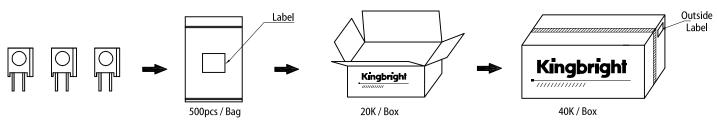


Notes:

- Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath
- temperature of 260°C

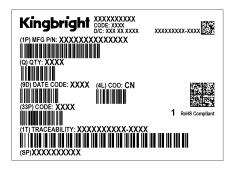
 2. Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).
- Do not apply stress to the epoxy resin while the temperature is above 85°C.
 Fixtures should not incur stress on the component when mounting and during soldering process.
- SAC 305 solder alloy is recommended.
 No more than one wave soldering pass

PACKING & LABEL SPECIFICATIONS









PRECAUTIONS

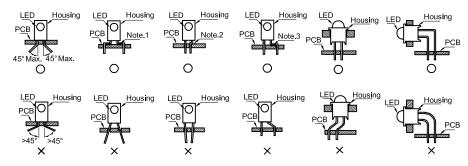
Storage Conditions

- 1. Avoid continued exposure to the condensing moisture environment and keep the product away from rapid transitions in ambient temperature.
- 2. LEDs should be stored with temperature ≤ 30°C and relative humidity < 60%.
- 3. Product in the original sealed package is recommended to be assembled within 72 hours of opening. Product in opened package for more than a week should be baked for 30 (+10/-0) hours at 85 ~ 100°C.

LED Mounting Method

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.

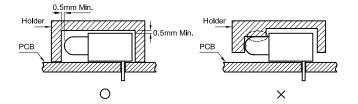
Note 1-3: Do not route PCB trace in the contact area between the leadframe and the PCB to prevent short-circuits.



○ " Correct mounting method " x " Incorrect mounting method

Lead Forming Procedures

- 1. During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during
- 2. The tip of the soldering iron should never touch the lens epoxy.
- 3. Through-hole LEDs are incompatible with reflow soldering.
- 4. If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.



PRECAUTIONARY NOTES

- The information included in this document reflects representative usage scenarios and is intended for technical reference only
- The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
- When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If customer usage exceeds the specified limits, Kingbright will not be responsible for any subsequent issues.

 The information in this document applies to typical usage in consumer electronics applications. If customer's application has special reliability requirements or have life-threatening
- liabilities, such as automotive or medical usage, please consult with Kingbright representative for further assistance
- The contents and information of this document may not be reproduced or re-transmitted without permission by Kingbright
- All design applications should refer to Kingbright application notes available at https://v



X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for LED Circuit Board Indicators category:

Click to view products by Kingbright manufacturer:

Other Similar products are found below:

568-0701-841F LTL-4221NH129 LTL-42DGNMHDP1 HLMP1521101 HLMP1523802F HLMP1700101F HLMP1700104F BHA-1564-G SMF-HM1530YD-305 SSF-LXH409SYSUGW AM2520EHSGD HLMP1301104F HLMP1385101F HLMP1421101 HLMP1503103F HLMP1503104F HLMP1700102F HLMP1700106F HLMP1700107F HLMP1790101F HLMP1790103F LTL-4211NHBP 5390H3 5390H5 551-2802F 552-0794-810F 553-0222-812F HT3-BC-T 564-0700-831F WP59BLGEW 103-3101-1231-403 5502407811F 550-3007-810F 551-3307MF 552080-1 573-2399-100F 592-2020-302F 5932-927-2701-3F SMF-HM1530SRD-509 SSF-LXH100MID SSF-LXH2103SRSRDRP SSF-LXH555USBW WP937SB/4YGW WP937EB2EGW HT3-BLU-T 551-0312-802F 553-0110-802F 6202T3-5VLC LTL-307G08A-D CMD57164